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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
10/708,066	02/06/2004	Roger Lam	FIS920030398US1	2065
29371 75	590 08/03/2005		EXAMINER	
CANTOR COLBURN LLP			CHERVINSKY, BORIS LEO	
55 GRIFFIN ROAD SOUTH BLOOMFIELD, CT 06002			ART UNIT	PAPER NUMBER
BLOOMFIELL), C1 00002		2835	
			DATE MAILED: 08/03/200	5

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)
	10/708,066	LAM ET AL.
Office Action Summary	Examiner	Art Unit
	Boris L. Chervinsky	2835
The MAILING DATE of this communication Period for Reply	appears on the cover sheet with the	he correspondence address
A SHORTENED STATUTORY PERIOD FOR RETHE MAILING DATE OF THIS COMMUNICATION - Extensions of time may be available under the provisions of 37 CF after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, and a light of the period for reply is specified above, the maximum statutory period for reply within the set or extended period for reply will, by standard part of the period by the Office later than three months after the maximum days and patent term adjustment. See 37 CFR 1.704(b).	N. R 1.136(a). In no event, however, may a reply to a. In reply within the statutory minimum of thirty (30 eriod will apply and will expire SIX (6) MONTHS tatute, cause the application to become ABAND	be timely filed) days will be considered timely. from the mailing date of this communication. ONED (35 U.S.C. § 133).
Status		
Responsive to communication(s) filed on <u>0</u> This action is FINAL . 2b) □ Since this application is in condition for all closed in accordance with the practice und	This action is non-final. wance except for formal matters,	·
Disposition of Claims		
 4) Claim(s) 1-20 is/are pending in the applicate 4a) Of the above claim(s) is/are withe 5) Claim(s) is/are allowed. 6) Claim(s) 1-20 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and continuous continuous	drawn from consideration.	
Application Papers		
9)☐ The specification is objected to by the Exam 10)☒ The drawing(s) filed on <u>06 February 2004</u> is Applicant may not request that any objection to Replacement drawing sheet(s) including the cor 11)☐ The oath or declaration is objected to by the	s/are: a) accepted or b) objee the drawing(s) be held in abeyance. rection is required if the drawing(s) is	See 37 CFR 1.85(a). objected to. See 37 CFR 1.121(d).
Priority under 35 U.S.C. § 119		
12) Acknowledgment is made of a claim for fore a) All b) Some * c) None of: 1. Certified copies of the priority docum 2. Certified copies of the priority docum 3. Copies of the certified copies of the papplication from the International Bur * See the attached detailed Office action for a	ents have been received. ents have been received in Application of the contraction of the	cation No eived in this National Stage
Attachment(s)		
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948)		il Date
 Information Disclosure Statement(s) (PTO-1449 or PTO/SB. Paper No(s)/Mail Date 	/08) 5) Notice of Inform 6) Other:	al Patent Application (PTO-152)

DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

2. Claims 1, 4, 6, 8, 11, 14, 17 and 19 are rejected under 35 U.S.C. 102(b) as being anticipated by Toy et al.

Toy discloses a semiconductor device packaging assembly, comprising: a chip module 10 mounted on a circuit board substrate 30; at least one integrated circuit chip 16 mounted on the substrate 10; a thermal interface layer 17 in contact with the at least one integrated circuit chip 16; a heat sink 20 in contact with the thermal interface layer 17 and at least one spacer member 47 in contact between said chip module 10 and the heat sink, wherein the at least one spacer member 47 is provided with an adhesive material 53, 53 on top and bottom surfaces thereof; the at least one spacer member 47 comprises a rigid material; the thermal interface layer 17 is the thermal interface pad and free of adhesive. The method steps of claims 8, 11 are necessitated by the device structure as disclosed by Toy et al.

Claim Rejections - 35 USC § 103

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

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4. Claims 3, 5, 7, 10, 12, 13, 16, 18 and 20 are rejected under 35 U.S.C. 103(a) as being unpatentable over Toy et al.

Toy discloses the claimed invention except specific materials such as phenolic resin for the spacer and epoxy as an adhesive. It would have been obvious to one having ordinary skill in the art at the time the invention was made to use phenolic resins and epoxy, since it has been held to be within the general skill of a worker in the art to select a known material on the basis of its suitability for the intended use as a matter of obvious design choice. *In re Leshin*, 125 USPQ 416.

Toy discloses the claimed invention except the size of thermal interface being 4 mil in compressed condition and 6 mil being in normal condition. This size depends on the properties of chosen material and as it is stated above the selection of known materials is within the general skill of a worker in the art therefore obvious.

5. Claims 2, 9 and 15 are rejected under 35 U.S.C. 103(a) as being unpatentable over Toy et al. in view of Boyer et al.

Toy discloses the claimed invention, as shown above, except the spacer being in cylindrical shape. Boyer discloses the spacer 32 of cylindrical shape placed between the heat sink and the substrate. It would have been obvious to one having ordinary skill in the art at the time the invention was made to use cylindrical spacer as disclosed by Boyer et al. in the device disclosed by Toy et al. as to simplify the structure.

Response to Arguments

6. Applicant's arguments filed on 07/07/05 have been fully considered but they are not persuasive. The applicant's argument that the element 20 is not a heat sink and the

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spacer is not disposed between the heat sink and the substrate is not convincing since the terminology used in the prior art is not necessarily to be matched with the terminology used in claims; the elements 20, 51 and 50 in combination can be considered as the heat sink because their primary function is to dissipate heat generated by the IC chip16. The applicant's argument that the element 47 is the sealing ring and not the spacer is not persuasive since the element 47 provides spacing between the heat sink 20 and the substrate 10 and again is the matter of terminology used.

Conclusion

7. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

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Any inquiry concerning this communication or earlier communications from the examiner should be directed to Boris L. Chervinsky whose telephone number is 571-272-2039. The examiner can normally be reached on 8-5.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Lynn D. Feild can be reached on 571-272-2800 ext. 35. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Men: l. Clums 8/2/5

BORIS CHÉRVINSKY PRIMARY EXAMINER